# MA3S795D, MA3S795E (MA795WA, MA795WK)

## Silicon epitaxial planar type

### For switching

### ■ Features

- High-density mounting is possible
- $\bullet$  Low forward voltage  $V_F$  , optimum for low voltage rectification:  $V_F$  < 0.3 V (at  $I_F$  = 1 mA)
- Optimum for high frequency rectification because of its short reverse recovery time (t<sub>rr</sub>)
- SS-Mini type 3-pin package

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter		Symbol	Rating	Unit
Reverse voltage (DC)		$V_R$	30	V
Peak reverse voltage		$V_{RM}$	30	V
Peak forward current	Series	$I_{FM}$	150	mA
	Double *		110	
Forward current (DC)	Series	$I_F$	30	mA
	Double *		20	
Junction temperature		T <sub>j</sub>	125	°C
Storage temperature		$T_{stg}$	-55 to +125	°C

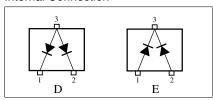
Note) \*: Value per chip

# Unit: mm 0.28±0.05 0.12±0.05 0

### Marking Symbol

• MA3S795D: M3D • MA3S795E: M3D

### Internal Connection



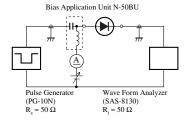
### ■ Electrical Characteristics $T_a = 25$ °C

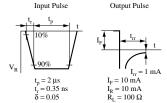
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Reverse current (DC)	$I_R$	$V_R = 30 \text{ V}$			30	μΑ
Forward voltage (DC)	V <sub>F1</sub>	$I_F = 1 \text{ mA}$			0.3	V
	V <sub>F2</sub>	$I_F = 30 \text{ mA}$			1	
Terminal capacitance	C <sub>t</sub>	$V_R = 1 \text{ V, } f = 1 \text{ MHz}$		1.5		pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = I_R = 10 \text{ mA}$		1		ns
		$I_{rr} = 1 \text{ mA}, R_L = 100 \Omega$				
Detection efficiency	η	$V_{in} = 3 V_{(peak)}$ , $f = 30 MHz$		65		%
		$R_L = 3.9 \text{ k}\Omega, C_L = 10 \text{ pF}$				

Note) 1. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

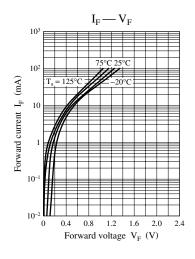
2. Rated input/output frequency: 2 GHz

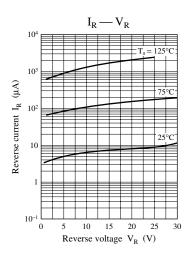
3. \*: t<sub>rr</sub> measuring instrument

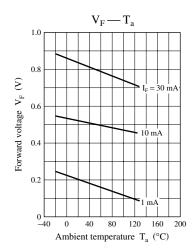


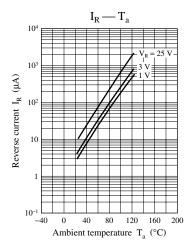


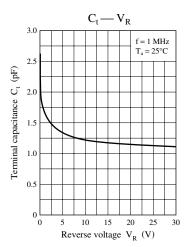
Note) The part number in the parenthesis shows conventional part number.











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